



PK1202(v1.0) October 8, 2024

100% Material Declaration Data Sheet for Zynq UltraScale+ UBVA494

Average Weight : 0.1810 g

Component	Substance Description	CAS # or Description	% of Component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon Die					0.052977	29.269%
	Silicon	7440-21-3	100.00	basis	0.052977	
Molding compound					0.041551	22.956%
	Filler (SiO2)	60676-86-0	84.00	Filler	0.034903	
	Epoxy resin	27610-48-6	8.00	Glue	0.003324	
	Hardener resin	25550-51-0	8.00	Glue	0.003324	
Dielectric					0.004903	2.709%
	Polyamic acid ester	trade secret	30.00	Main material	0.001471	
	N-methyl-2-pyrrolidone	872-50-4	50.00	Solvent	0.002451	
	Other components	trade secret	4.50	Main material	0.000221	
	Tetraethylene glycol dimethacrylate	109-17-1	3.00	Main material	0.000147	
	Ethyl lactate	97-64-3	12.50	Main material	0.000613	
Interconnect					0.011220	6.199%
	Copper	7440-50-8	100.00	Main material	0.011220	
Solder Ball					0.070349	38.87%
	Tin	7440-31-5	92.40	Main material	0.065003	
	Silver	7440-22-4	4.06	Main material	0.002856	
	Bismuth	7440-69-9	2.98	Main material	0.002096	
	Copper	7440-50-8	0.50	Main material	0.000352	
	Nickel	7440-02-0	0.06	Main material	0.000042	

Revision History

Date	Version	Description of Revisions
10/8/2024	1.0	Initial AMD Release.

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